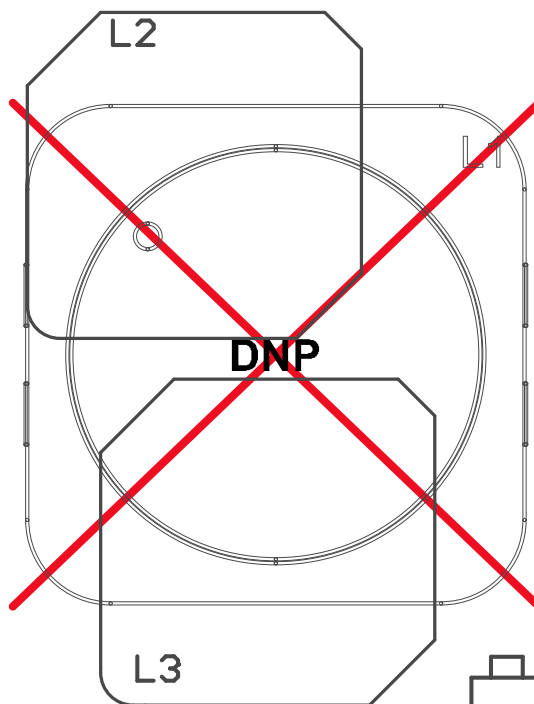
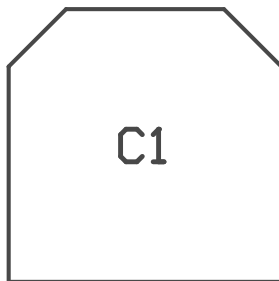
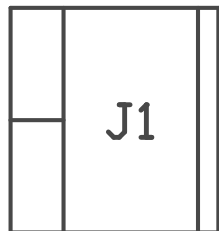


TP1



TP2

R11



TP7

R5

C12

C11

C10

R2

R10

C9

R8

C8



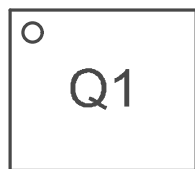
R7

R3

R9

R4

TP6

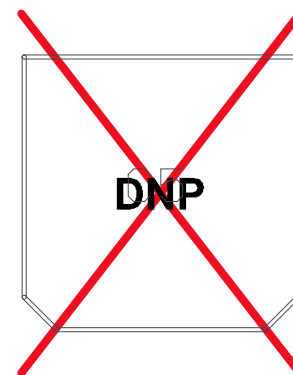


TP4

C4

C3

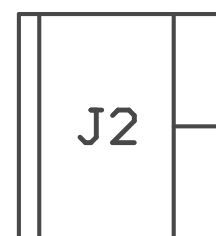
R1



C6

C7

TP5



TP3

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